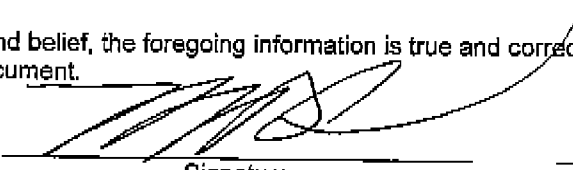


Client Code: CHEDKC.003AUS

**RECORDATION FORM COVER SHEET  
PATENTS ONLY**

To the Director, U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies): (List using letters or numbers for multiple parties)</p> <p>1. Han Su Lee 2. Byeong Do Lee 3. Sung Sig Min 4. Byung Choon Lee</p> <p>Additional name(s) of conveying party(ies) attached? ( ) Yes (X) No</p>	<p>2. Name and address of receiving party(ies):</p> <p><b>Name:</b> CHEIL INDUSTRIES, INC. <b>Internal Address:</b> <b>Street Address:</b> 290 Gongdan-dong, Gumi-shi, Gyung-sangbuk-do, 730-030, REPUBLIC OF KOREA</p> <p>Additional name(s) of receiving party(ies) attached? ( ) Yes (X) No</p>
<p>3. Nature of conveyance:</p> <p>(X) Assignment ( ) Security Agreement ( ) Merger ( ) Change of Name ( ) Other:</p> <p>Execution Date: (List as in section 1 if multiple signatures) (1) February 16, 2006; (2) February 16, 2006; (3) February 16, 2006; and (4) February 16, 2006.</p>	<p>4. US or PCT Application number(s) or US Patent number(s):</p> <p>(X) Patent Application No.: 11/323,646 Filing Date: December 29, 2005</p> <p>Additional numbers attached? ( ) Yes (X) No</p>
<p>5. Party to whom correspondence concerning document should be mailed:</p> <p><b>Customer No.</b> 20,995 <b>Address:</b> Knobbe, Martens, Olson &amp; Bear, LLP 2040 Main Street, 14<sup>th</sup> Floor Irvine, CA 92614 <b>Return Fax:</b> (949) 760-9502 <b>Attorney's Docket No.:</b> CHEDKC.003AUS</p>	<p>6. Total number of applications and patents involved: 1</p>
<p>7. Total fee (37 CFR 1.21(h)): \$40 (X) Authorized to be charged to deposit account</p>	<p>8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.</p>
<p>9. Statement and signature.</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.</p> <p><u>Mincheol Kim</u> Name of Person Signing</p> <p> Signature</p> <p><u>February 22, 2006</u> Date</p> <p>51,306 Registration No.</p> <p>Total number of pages including cover sheet, attachments and document: 3</p>	

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**PATENT**  
**REEL: 017280 FRAME: 0359**

Application No.: 11/323,646  
 Filing Date: December 29, 2005

PATENT  
 Client Code: CHEDKC.003AUS  
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### ASSIGNMENT

WHEREAS, We, the undersigned, have invented certain new and useful improvements in an **IMPACT MODIFIER FOR A POLYMER COMPOSITION AND METHOD FOR PREPARING THE SAME** for which we have executed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, CHEIL INDUSTRIES, INC. (hereinafter "ASSIGNEE"), a Korean corporation with its principal place of business at 290 Gongdan-dong, Gumi-shi, Gyung-sangbuk-do 730-030, Republic of Korea, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

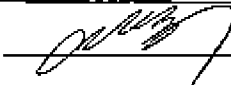
NOW, THEREFORE, in view of valuable considerations, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE DO HEREBY sell, assign, transfer, and convey to ASSIGNEE, his successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Full name of inventor: Han Su LEE

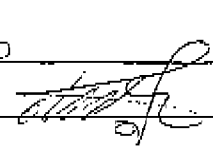
Date: Feb. 16, 2006

Inventor's signature 

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Full name of inventor: Byeong Do LEE

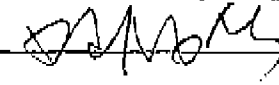
Date: Feb. 16, 2006

Inventor's signature 

Residence: 332-2 Gochun-dong, Uiwang-si, Gyeonggi-do 427-711, Republic of Korea

Full name of inventor: Sung Sig MIN

Date: Feb. 16, 2006

Inventor's signature 

Residence: 101-1602 Geunho Apt., Yumchang-dong, Gangseo-gu, Seoul 157-040, Republic of Korea

Application No.: 11/323,646  
Filing Date: December 29, 2005

**PATENT**  
Client Code: CHEDKC.003AUS  
Page 2

Full name of inventor: Byung Choon LEE

Date: 2006. 2. 16

Inventor's signature



Residence: 265-386 Hongseun-3dong, Seodaemun-gu, Seoul 120-846, Republic of Korea

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